Notification Number: 20160825000 Notification Date: Sept 06, 2016
Customer Contact: PCN Manager Dept: Quality Services Change Type: Assembly Site Design Wafer Bump Site Assembly Process Mechanical Specification Test Site Wafer Bump Process Mechanical Specification Test Site Wafer Fab Site Packing/Shipping/Labeling Test Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: AM26C31 SLLS1030 - DECEMBER 1990 - REVISED JUNE 2018 **Www.ti.com** Changes from Revision N (October 2011) to Revision O Page - Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Leyou'ce Ection, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. Deleted Ordering Information table, see POA at the end of the data sheet. 1 Changed Thermal Information table. 5 The datasheet number will be changing. Device Family Change From: Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): The cotanges impact. This is a specification change announcement only. There are no changes to the actual device
Assembly Site
Assembly Site
Assembly Process Assembly Materials Part number change Wafer Bump Material Wafer Bump Process Mechanical Specification Test Site Packing/Shipping/Labeling Test Site Wafer Fab Site Wafer Fab Materials Wafer Fab Materials Wafer Fab Process Notification Details Pescription of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: AM26C31 SLLS1030 - DECEMBER 1990 - REVISED JUNE 2016 Www.tl.com Changes from Revision N (October 2011) to Revision O Page Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. Deleted Ordering Information table, see POA at the end of the data sheet. Changed Thermal Information table, see POA at the end of the data sheet. Changed Thermal Information table. Device Family Change From: Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Assembly Materials Mechanical Specification Test Site Mechanical Specification Test Site Mafer Fab Site Wafer Fab Site Wafer Fab Materials Wafer Fab Materials Wafer Fab Materials Wafer Fab Process Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: AM26C31 SULS10300 - DECEMBER 1990 - REVISED JUNE 2016 - Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. Deleted Ordering Information table, see POA at the end of the data sheet. Device Family Change Thermal Information table Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Mechanical Specification Test Site Wafer Fab Site Wafer Fab Materials Wafer Fab Materials Wafer Fab Process Wafer Fab Materials Wafer Fab Process Wa
Packing/Shipping/Labeling
Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: AM26C31 SLLS1030 - DECEMBER 1990 - REVISED JUNE 2018 Lydated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. Deleted Ordering Information table, see POA at the end of the data sheet. 1 Changed Thermal Information table. 5 The datasheet number will be changing. Device Family Change From: Change From: Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/syymlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Notification Details Description of Change: Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: AM26C31 SILIS1030 - DECEMBER 1990 - REVISED JUNE 2016 Changes from Revision N (October 2011) to Revision O Page Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. 1 Deleted Ordering Information table, see POA at the end of the data sheet. 1 Changed Thermal Information table. 5 The datasheet number will be changing. Device Family AM26C31 Change From: Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: AM26C31 SLLS1030 - DECEMBER 1990 - REVISED JUNE 2016 Changes from Revision N (October 2011) to Revision O Page Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. 1 Deleted Ordering Information table, see POA at the end of the data sheet. 1 Changed Thermal Information table. 5 The datasheet number will be changing. Device Family AM26C31 Change From: Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is updated as seen in the change revision history below: Texas
TEXAS INSTRUMENTS AM26C31 SLLS1030 - DECEMBER 1990 - REVISED JUNE 2016 - Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Loyout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. - Deleted Ordering Information table, see POA at the end of the data sheet. - Changed Thermal Information table - Solution of the datasheet number will be changing. Device Family - Change From: - Change To: - AM26C31 These changes may be reviewed at the datasheet links provided http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
AM26C31 SLLS103O - DECEMBER 1990 - REVISED JUNE 2016 Changes from Revision N (October 2011) to Revision O Page - Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. - Deleted Ordering Information table, see POA at the end of the data sheet. - Changed Thermal Information table. 5 The datasheet number will be changing. Device Family AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
AM26C31 SLLS103O - DECEMBER 1990 - REVISED JUNE 2016 Changes from Revision N (October 2011) to Revision O Page - Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. - Deleted Ordering Information table, see POA at the end of the data sheet. - Changed Thermal Information table - Change To: The datasheet number will be changing. Device Family Change From: Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Changes from Revision N (October 2011) to Revision O Page Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. Deleted Ordering Information table, see POA at the end of the data sheet. Changed Thermal Information table. Device Family Change From: Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Updated the Features section and added the Applications section, the Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section. Deleted Ordering Information table, see POA at the end of the data sheet. Changed Thermal Information table. The datasheet number will be changing. Device Family Change From: AM26C31 Change From: Change To: AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section
Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section
Packaging, and Orderable Information section
 Changed Thermal Information table
The datasheet number will be changing. Device Family AM26C31 Change From: SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Device Family AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Device Family AM26C31 SLLS103N SLLS103O These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/am26c31.pdf Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Reason for Change: To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
To more accurately reflect device characteristics. Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device
to the actual device
Changes to product identification resulting from this notification:
None.
Product Affected:
5962-9163901M2A AM26C31CDR AM26C31IDE4 AM26C31IPWRG4
5962-9163901MEA AM26C31CDRE4 AM26C31IDG4 AM26C31MFKB
5962-9163901MFA AM26C31CDRG4 AM26C31IDR AM26C31MJB
5962-9163901Q2A AM26C31CN AM26C31IDRE4 AM26C31MWB
5962-9163901QEA AM26C31CNE4 AM26C31IDRG4 AM26C31QD
5962-9163901QFA AM26C31CNSR AM26C31IN AM26C31QDG4
AM26C31CD AM26C31CNSRG4 AM26C31INE4 AM26C31QDR

AM26C31CDBRG4	AM26C31IDBR	AM26C31IPW	
AM26C31CDE4	AM26C31IDBRE4	AM26C31IPWG4	
AM26C31CDG4	AM26C31IDBRG4	AM26C31IPWR	

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com